

Organizational Chart

North America

Japan

Europe

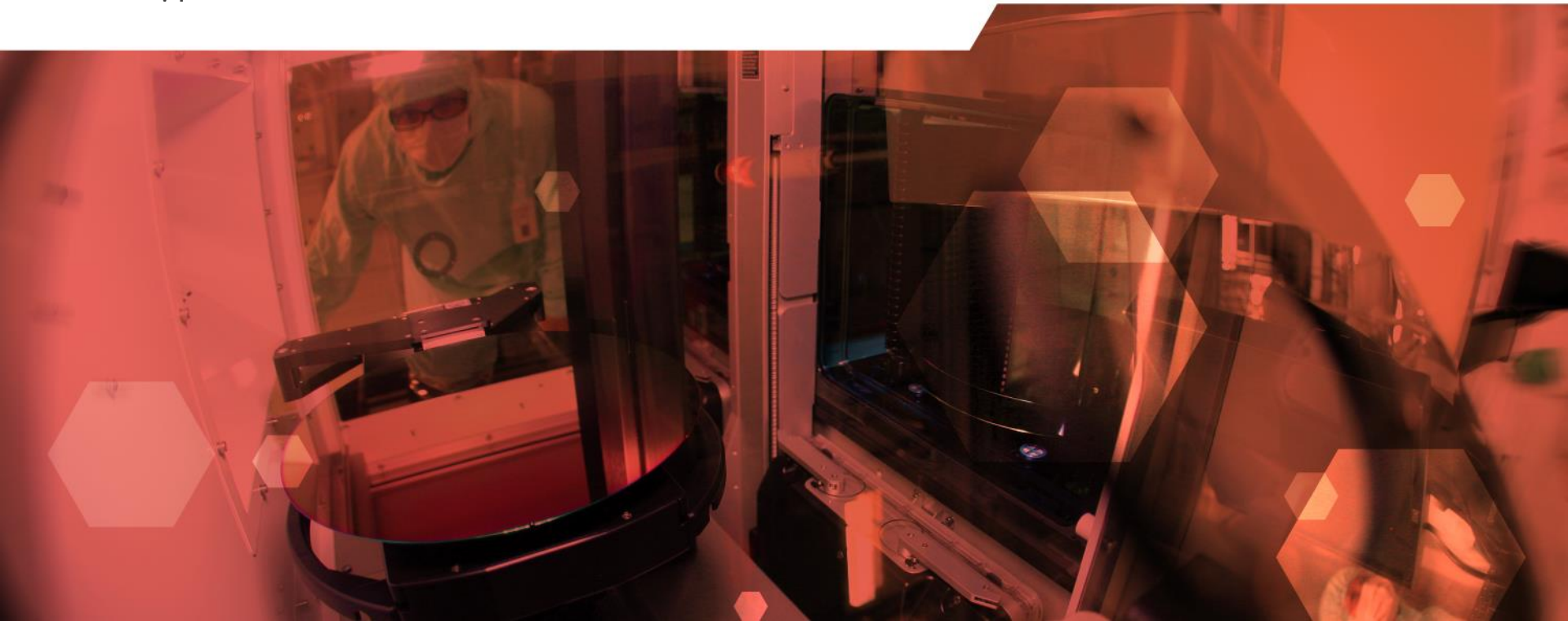
Last Updated: April 2019

v1

Korea

Taiwan

China



Global Technical Committee (GTC) and Technical Committee (TC) Chapters

Global Technical Committee	Locale						
		China	<u>Europe</u>	<u>Japan</u>	Korea	<u>North America</u>	Taiwan
EH&S				TCC		TCC	TCC
Facilities				TCC	TCC	TCC	
Gases			TCC	TCC		TCC	
Liquid Chemicals			TCC	TCC		TCC	
FPD Materials & Components				TCC	TCC		
FPD Metrology				TCC	TCC		TCC
MEMS/NEMS						TCC	

Legend:

TCC – The Locale has a TC Chapter of the global technical committee.

CFG – The Locale has a TC Chapter Formation Group, as defined in PM 6.5, of the global technical committee.

Note 1: An underlined Locale has an RSC and may also be referred as “a Region” (e.g., “Europe Region”).

Note 2: Some TC Chapters of different global technical committees jointly hold a meeting (indicated in red rectangles).

Global Technical Committee	Locale	China	<u>Europe</u>	<u>Japan</u>	Korea	<u>North America</u>	Taiwan
	Traceability				TCC		TCC
Information & Control			TCC	TCC	TCC	TCC	TCC
Metrics			TCC	TCC		TCC	
Physical Interfaces & Carriers			TCC	TCC		TCC	
Automation Technology			TCC	TCC			TCC
Photovoltaic		TCC		TCC		TCC	TCC
PV Materials		TCC	TCC	TCC		TCC	

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* In NA, Micropatterning is traditionally called Microlithography

Global Technical Committee	Locale						
		China	<u>Europe</u>	<u>Japan</u>	Korea	<u>North America</u>	Taiwan
Micropatterning (Microlithography*)						TCC	
Silicon Wafer			TCC	TCC		TCC	
Compound Semiconductor Materials			TCC	TCC		TCC	
HB-LED		TCC				TCC	
3D Packaging & Integration**				TCC		TCC	TCC
Automated Test Equipment (ATE)						TCC	

Legend:

TCC – The Locale has a TC Chapter of the global technical committee.

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Note 1: An underlined Locale has an RSC and may also be referred as “a Region” (e.g., “Europe Region”).

* In NA, Micropatterning is traditionally called Microlithography

** 3DS-IC GTC and Assembly & Packaging GTC were integrated into one new GTC as 3D Packaging & Integration GTC in July 2017.

Regional Standards Committee (RSC) Organizations

SEMI Europe RSC Organization

Co-Chairs: Bert Planting – ASML, Werner Bergholz – International Standards Consulting

Vice-Chair: Frank Petzold – Trustsec

Europe Chapter of Automation Technology Global Technical Committee

C: Christian Hoffmann – PEER Group

Europe Chapter of Liquid Chemicals Global Technical Committee

C: Jochen Ruth – Pall Corporation

Europe Chapter of Physical Interfaces & Carriers Global Technical Committee

C: Alfred Honold – InReCon

C: Frank Petzold – Trustsec

Europe Chapter of Compound Semiconductor Materials Global Technical Committee

C: Arnd Weber – SiCrystal

Europe Chapter of Information & Control Global Technical Committee

C: Alfred Honold – InReCon

C: Frank Petzold – Trustsec

Europe Chapter of PV Materials Global Technical Committee

C: Peter Wagner – Consultant

C: Christian Hagendorf – Fraunhofer CSP

Europe Chapter of Gases Global Technical Committee

C: Jochen Ruth – Pall Corporation

Europe Chapter of Metrics Global Technical Committee

C: Alfred Honold – InReCon

C: Lothar Pfitzner – FhG IISB

Europe Chapter of Silicon Wafer Global Technical Committee

C: Werner Bergholz – International Standards Consulting

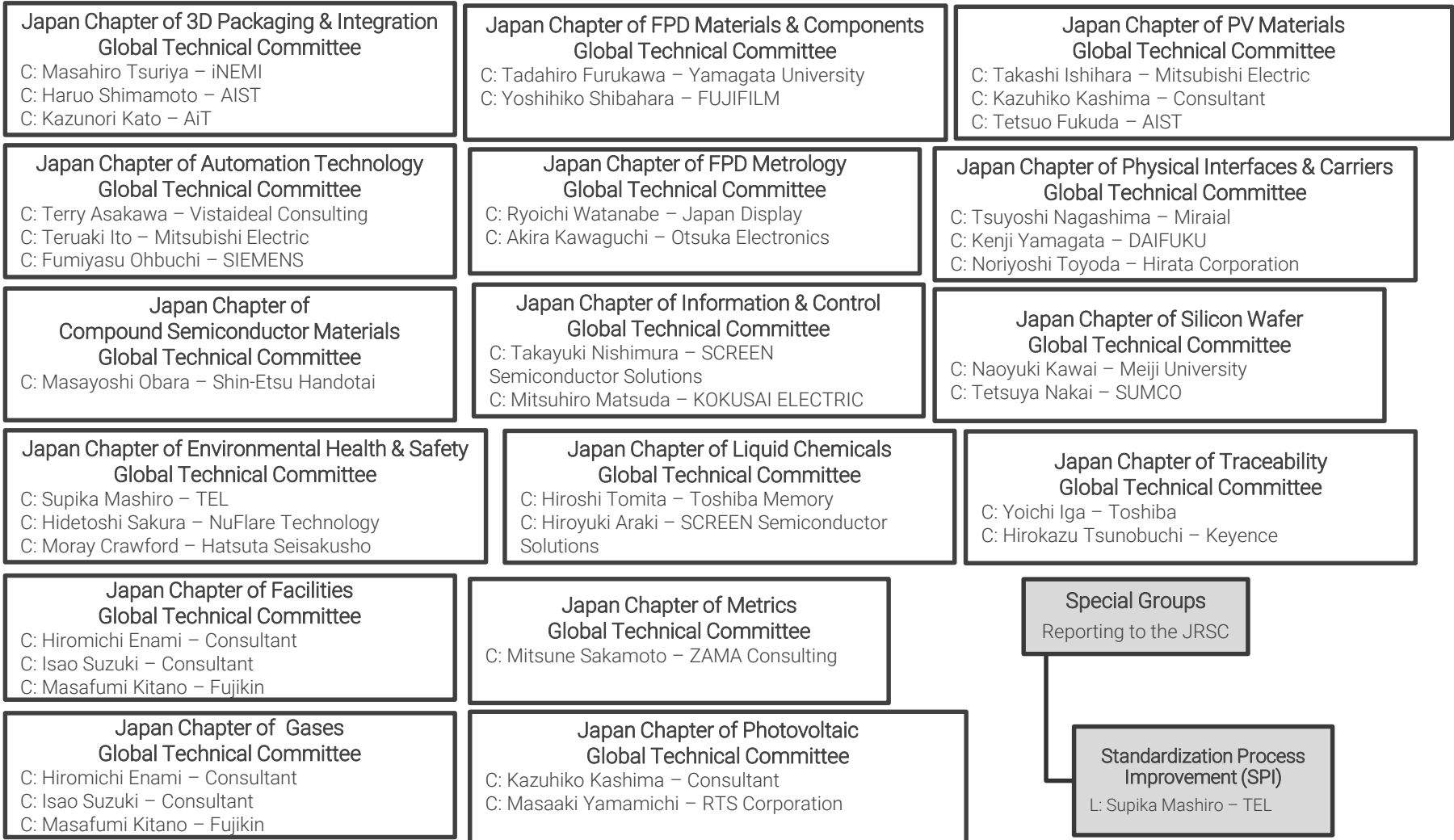
C: Peter Wagner – Consultant

C: Fritz Passek - Siltronic

SEMI Japan RSC Organization

Co-Chairs: Kenji Yamagata – Daifuku, Hidetoshi Sakura – NuFlare Technology

Vice-Chair: Supika Mashiro – TEL



SEMI North America (NA) RSC Organization – NA Locale

Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering

Vice-Chair: Brian Rubow – Cimatrix



SEMI North America RSC Organization – China Locale

Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering

Vice-Chair: Brian Rubow – Cimatrix

China Chapter of Photovoltaic
Global Technical Committee
C: Guangchun Zhang – CanadianSolar

China Chapter of PV Materials
Global Technical Committee
C: Guangchun Zhang – CanadianSolar

China Chapter of HB-LED
Global Technical Committee
C: Hongbo Zuo – AURORA
C: Jiangbo Wang – HC SemiTek

SEMI North America RSC Organization – Korea Locale

Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering

Vice-Chair: Brian Rubow – Cimatrix



SEMI North America RSC Organization – Taiwan Locale

Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering

Vice-Chair: Brian Rubow – Cimatrix

**Taiwan Chapter of 3D Packaging & Integration
Global Technical Committee**

C: Wendy Chen – King Yuan Electronics

C: Chien-Chung Lin – ITRI

C: Roger Hwang – ASE

**Taiwan Chapter of Flat Panel Display
Global Technical Committee**

C: Mike Yao – CMS/ITRI

C: Jia-Ming Liu – TDMDA

**Taiwan Chapter of Automation Technology
Global Technical Committee**

C: K.C. Chou – ASE

C: Jen-Hui Tsai – ITRI

C: Gwo-Sheng Peng – ITRI/CMS

C: Yung-Mao Zheng – MIRDC

**Taiwan Chapter of Information & Control
Global Technical Committee**

C: Robert Chien – TSMC

**Taiwan Chapter of Environmental Health & Safety
Global Technical Committee**

C: Shuh-Woei Yu – SAHTECH

**Taiwan Chapter of Photovoltaic
Global Technical Committee**

C: T.C. Wu – CMS/ITRI

C: J.S. Chen – TeraSolar

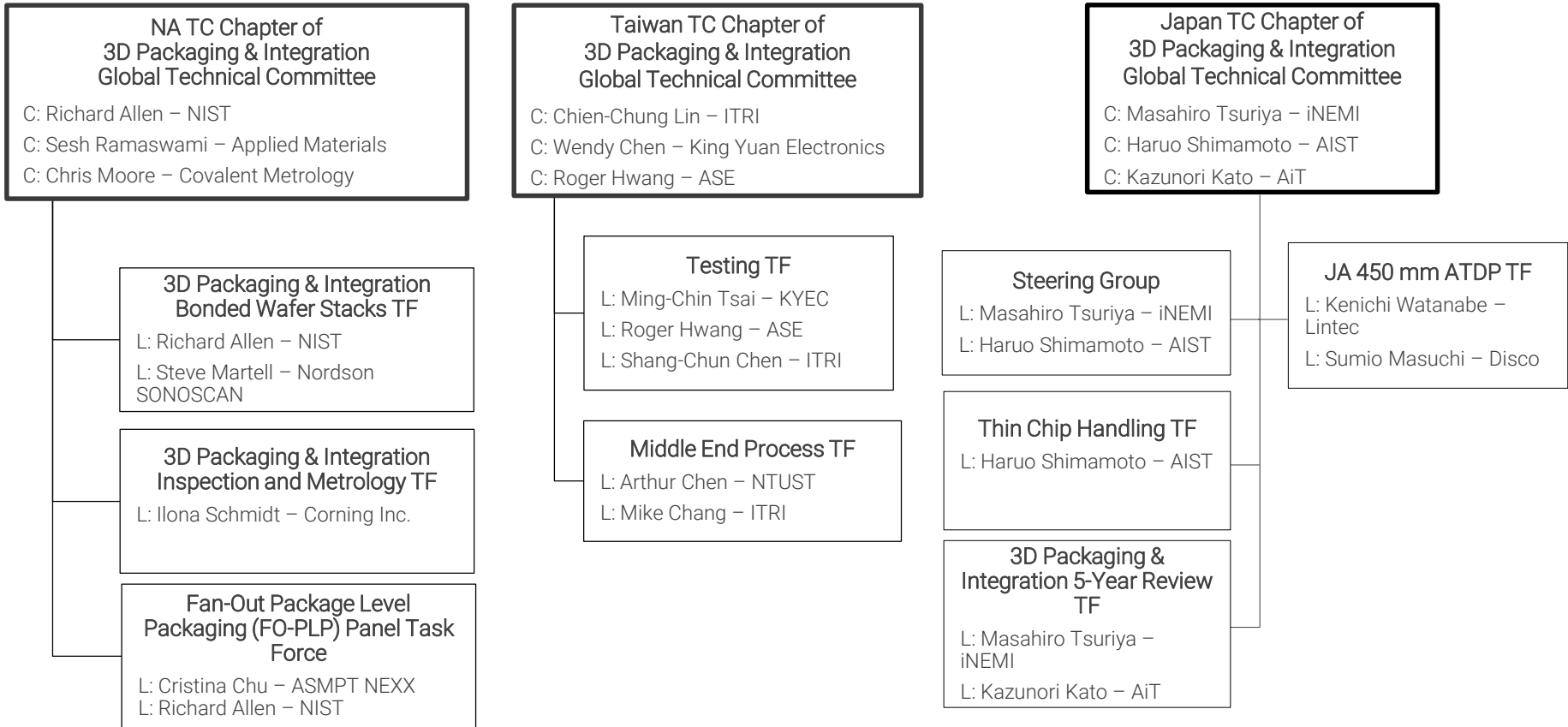
C: Ray Sung – UL Taiwan

ISC Taiwan Advisor

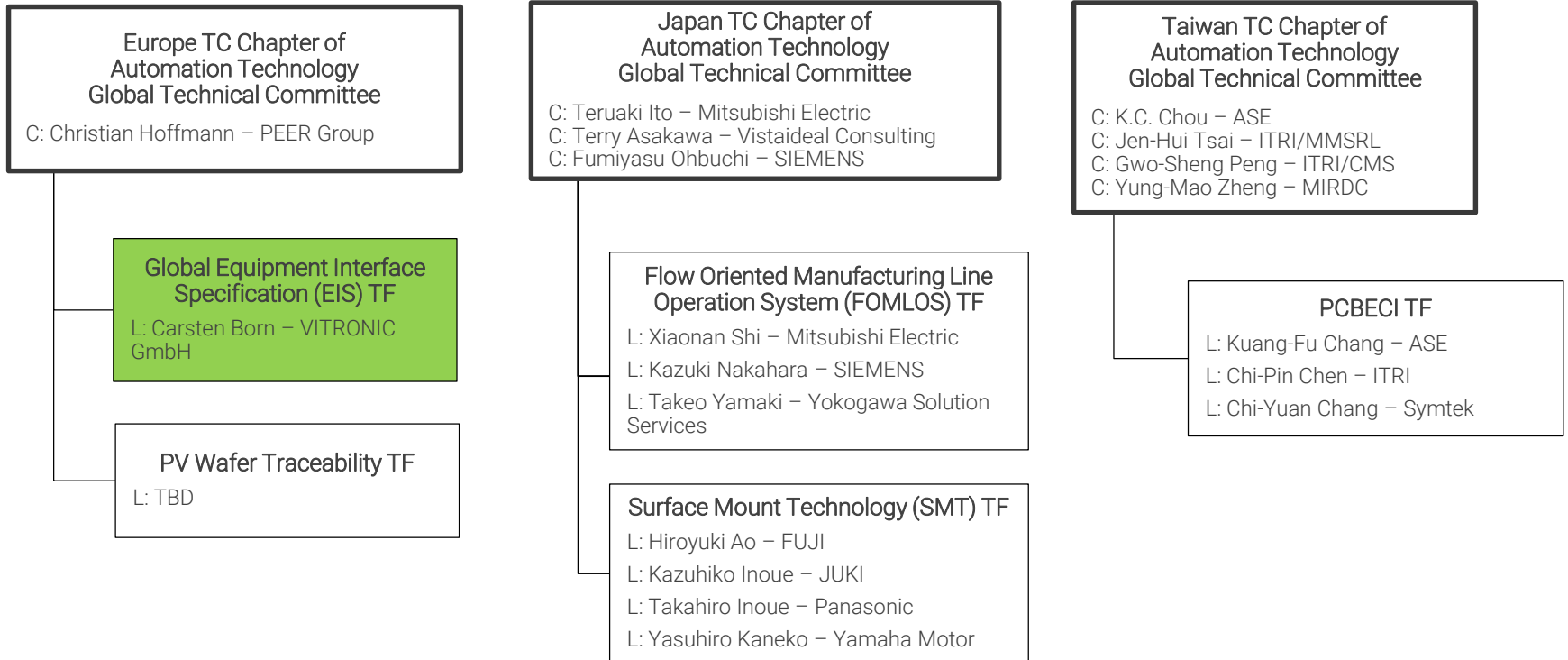
Tzeng-Yow Lin – CMS/ITRI


Organization of Each TC Chapter

3D Packaging & Integration (3DP&I) Global Technical Committee

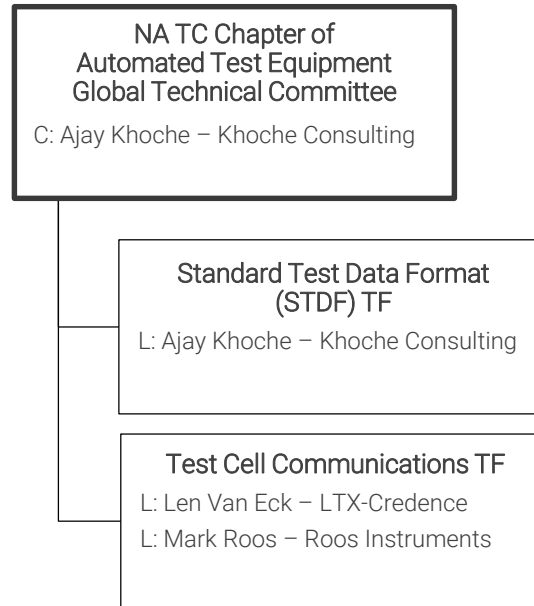


Automation Technology (AT) Global Technical Committee

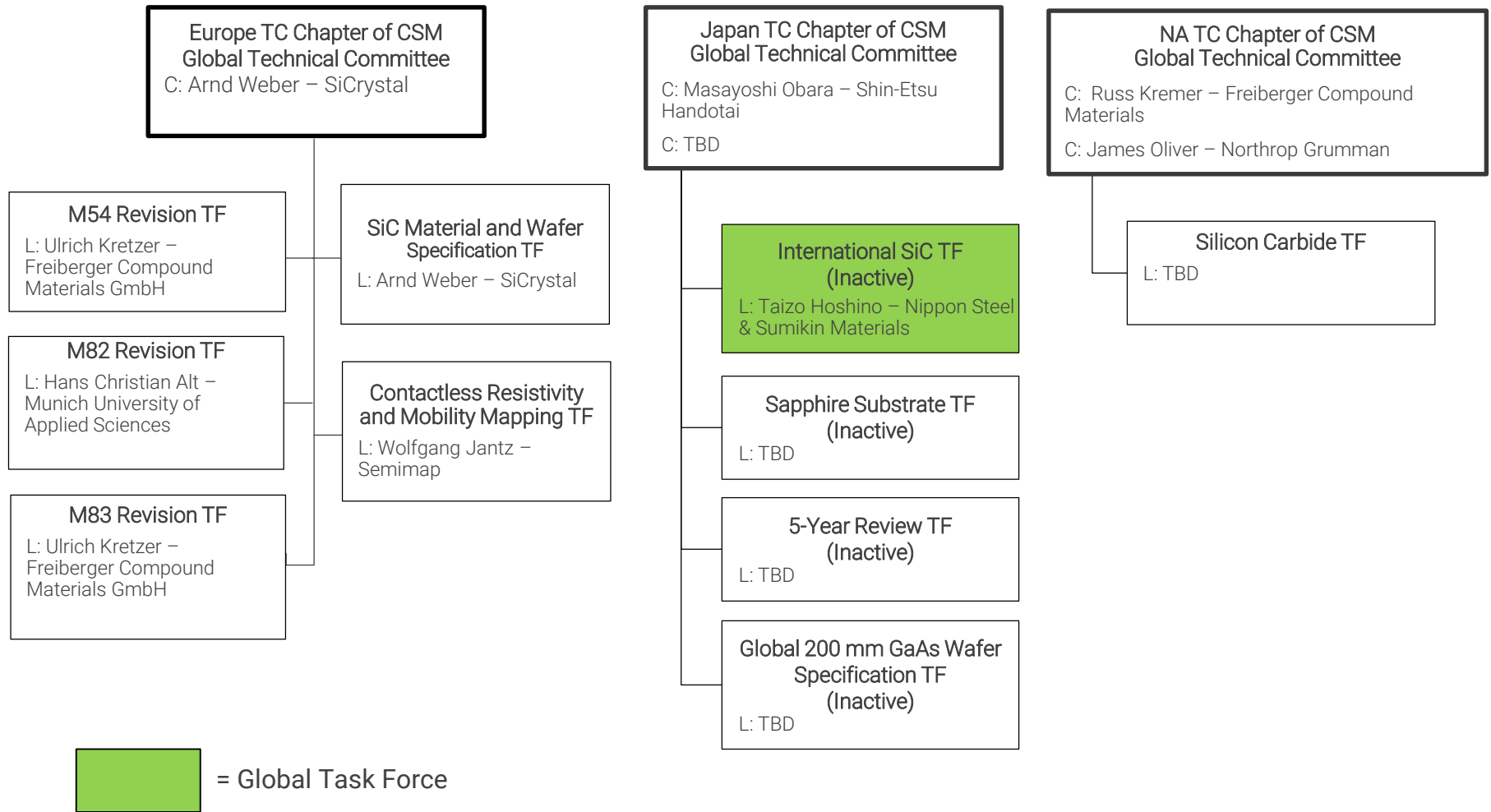


 = Global Task Force

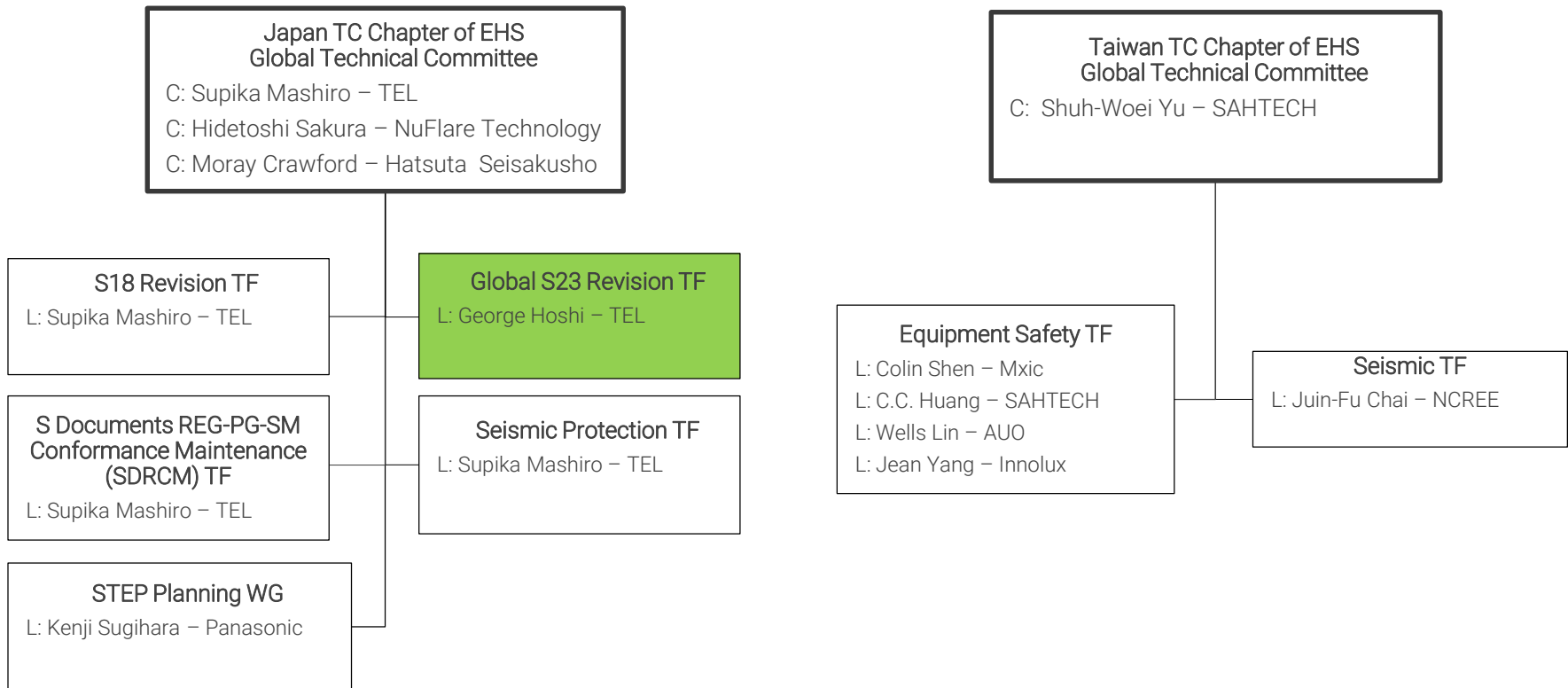
Automated Test Equipment (ATE) Global Technical Committee




Compound Semiconductor Materials (CSM) Global Technical Committee

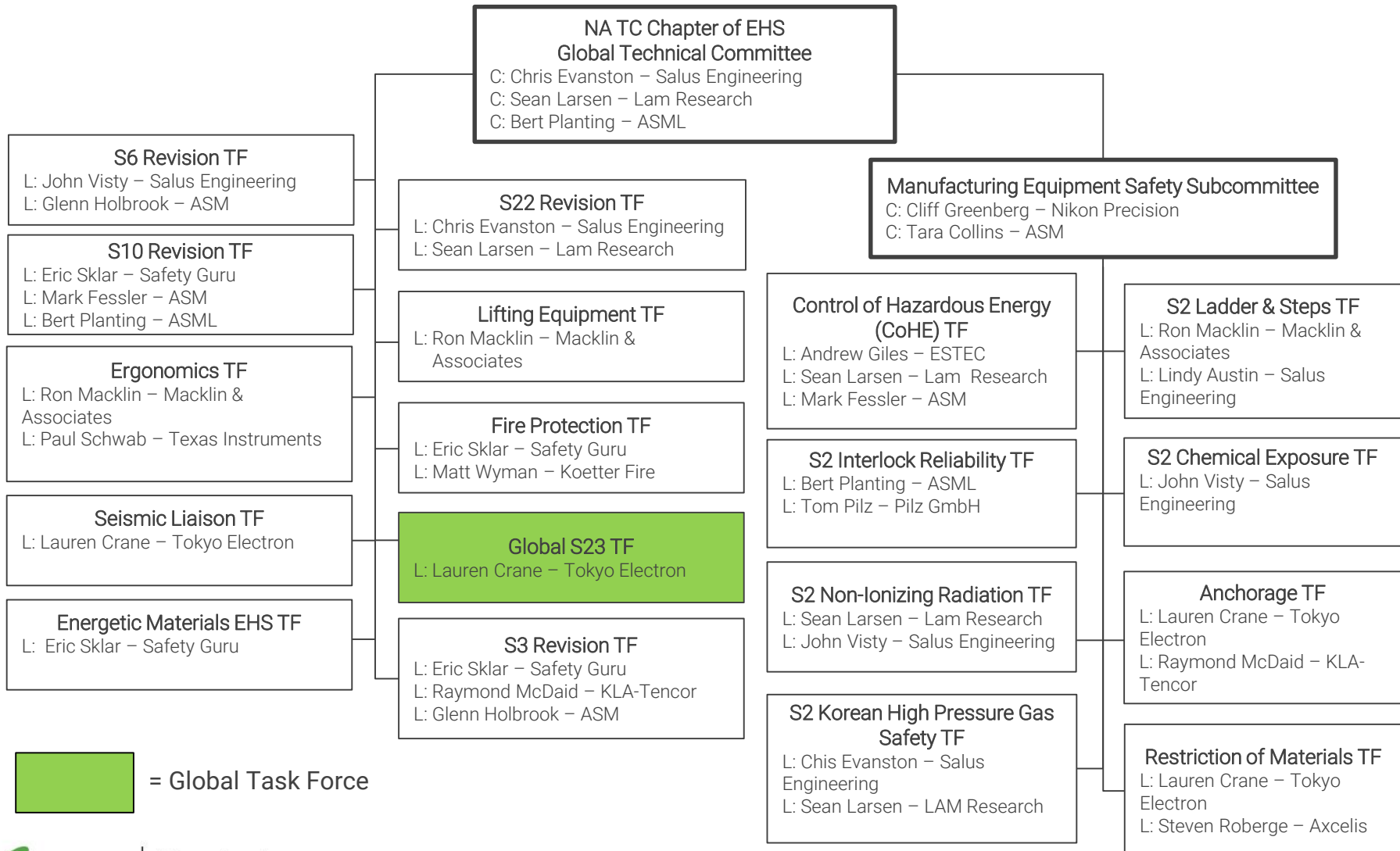


Environmental, Health & Safety (EH&S) Global Technical Committee



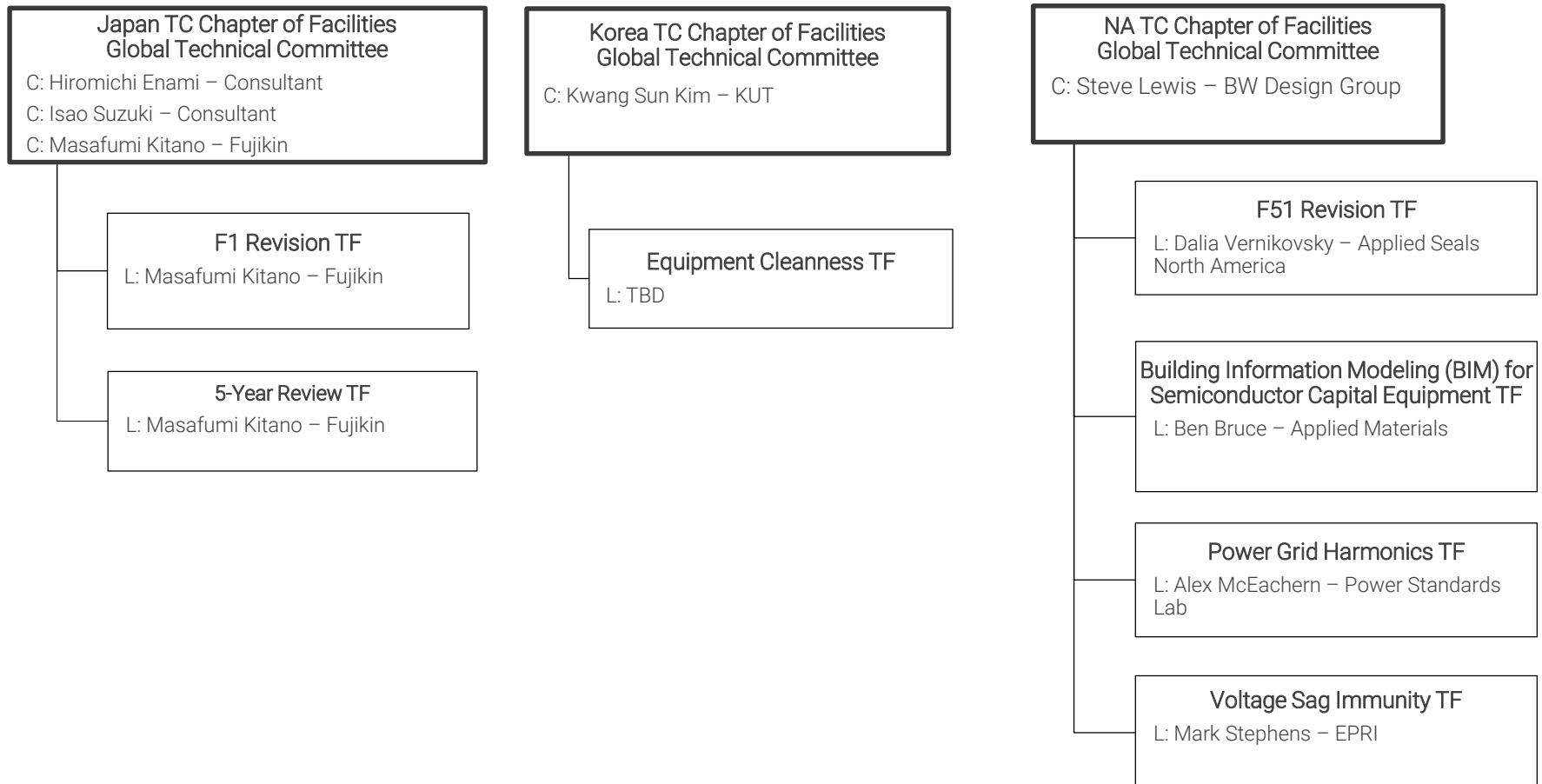
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Environmental, Health & Safety (EH&S) Global Technical Committee

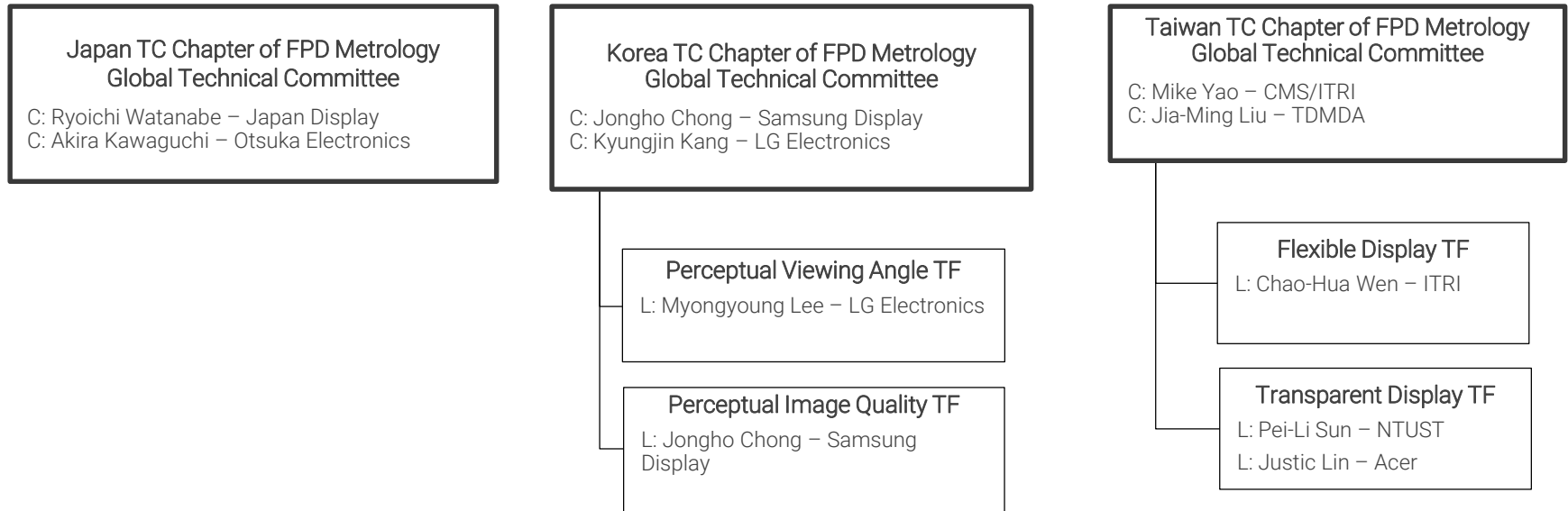


Facilities

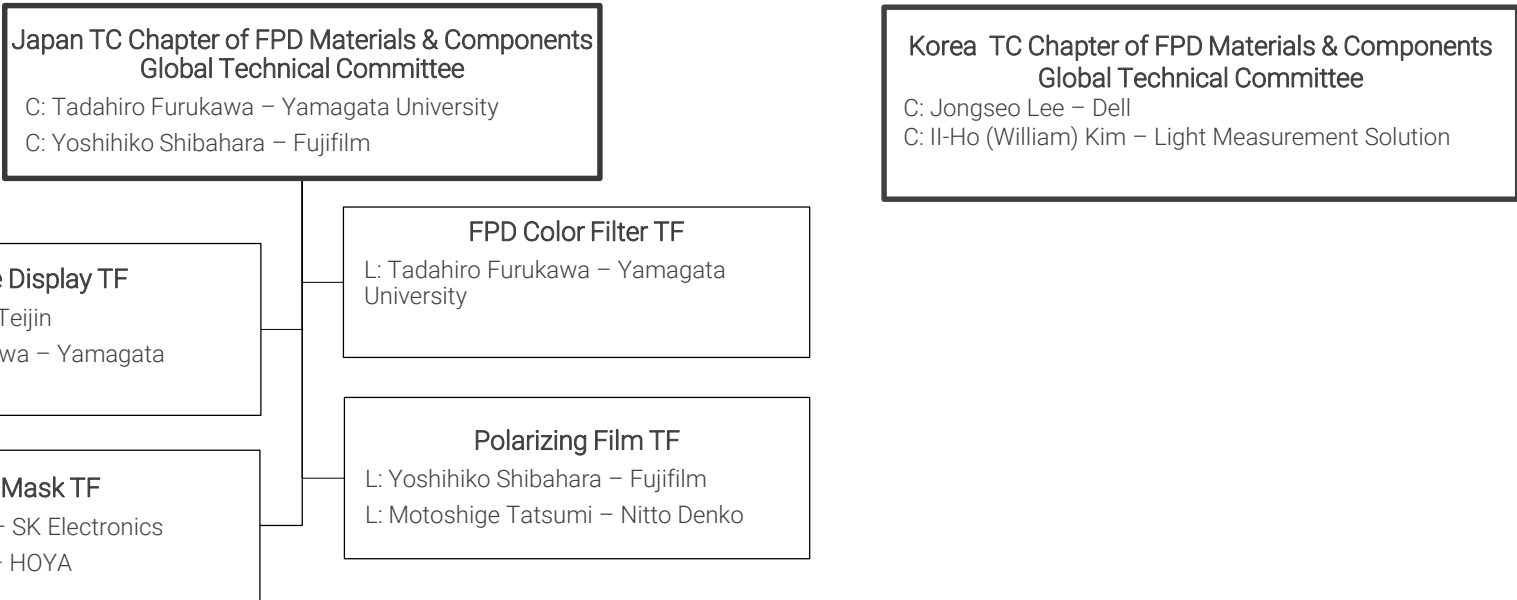
Global Technical Committee



FPD Metrology Global Technical Committee



FPD Materials & Components Global Technical Committee



Gases

Global Technical Committee

**Europe TC Chapter of Gases
Global Technical Committee**
C: Jochen Ruth – Pall Corporation

**Permeation Tubes for Trace
Moisture Calibration TF**
L: Jean-Marie Collard – Solvay
Chemicals
L: Jim McKinley – KIN-TEK

Cleaning Gases TF
L: Jean-Marie Collard – Solvay
Chemicals

**Japan TC Chapter of Gases
Global Technical Committee**
C: Hiromichi Enami – Consultant
C: Isao Suzuki – Consultant
C: Masafumi Kitano – Fujikin

**NA TC Chapter of Gases
Global Technical Committee**
C: Mohamed Saleem – Brooks
Instrument

Filters & Purifiers TF
L: Mohamed Saleem – Brooks
Instrument
L: Yanli Chen – UCT

Heater Jacket TF
L: Matt Milburn – UCT
L: David Colquhoun –
BriskHeat

Mass Flow Controller TF
L: Mohamed Saleem –
Brooks Instrument
L: Erica Kitano – Fujikin

Gases Specification TF
L: Mohamed Saleem –
Brooks Instrument
L: Thomas Fritz – WIKA

**Materials of Construction Gas
Delivery Systems TF**
L: Bill Kiiikvee – AP Tech

**Pressure Measurement TF
(Inactive)**
L: Yanli Chen – UCT
L: Jeff Christian – WIKA

**Surface Mount Sandwich
Component Dimensions TF
(Inactive)**
L: Matt Milburn – UCT

HB-LED

Global Technical Committee

China TC Chapter of HB-LED Global Technical Committee

C: Hongbo Zuo – AURORA
C: Jiangbo Wang – HC SemiTek

Single Crystal Sapphire TF

L: Yong Ji – Guizhou Haotian Optoelectronics Technology
L: Xinhong Yang – AURORA

Sapphire Single Crystal Ingot TF

L: Hongbo Zuo – AURORA

GaN based LED Epitaxial Wafer TF

L: Jiangbo Wang – HC SemiTek

Sapphire Single Crystal Orientation TF (Inactive)

L: Songbin Zhao – DDXDF

Patterned Sapphire Substrate TF

L: Jianzhe Liu – ECBO

HB-LED Equipment Communication Interface TF

L: Steven Lee – AMEC
L: Clare Liu – Cimatrix

NA TC Chapter of HB-LED Global Technical Committee

C: Mike Feng – Silian
C: Chris Moore – Covalent Metrology
C: Andrew Kim – InnovationforX

Patterned Sapphire Substrate (PSS) TF

L: Open

HB-LED Equipment Communication Interfaces TF (Inactive)

L: Brian Rubow – Cimatrix

HB-LED Equipment Automation Interfaces TF (Inactive)

L: Daniel Babbs – Brooks Automation
L: Jeff Felipe – Entegris

Test Methods TF (Inactive)

L: Peter Wagner – Self

HB-LED Wafer TF

L: Open

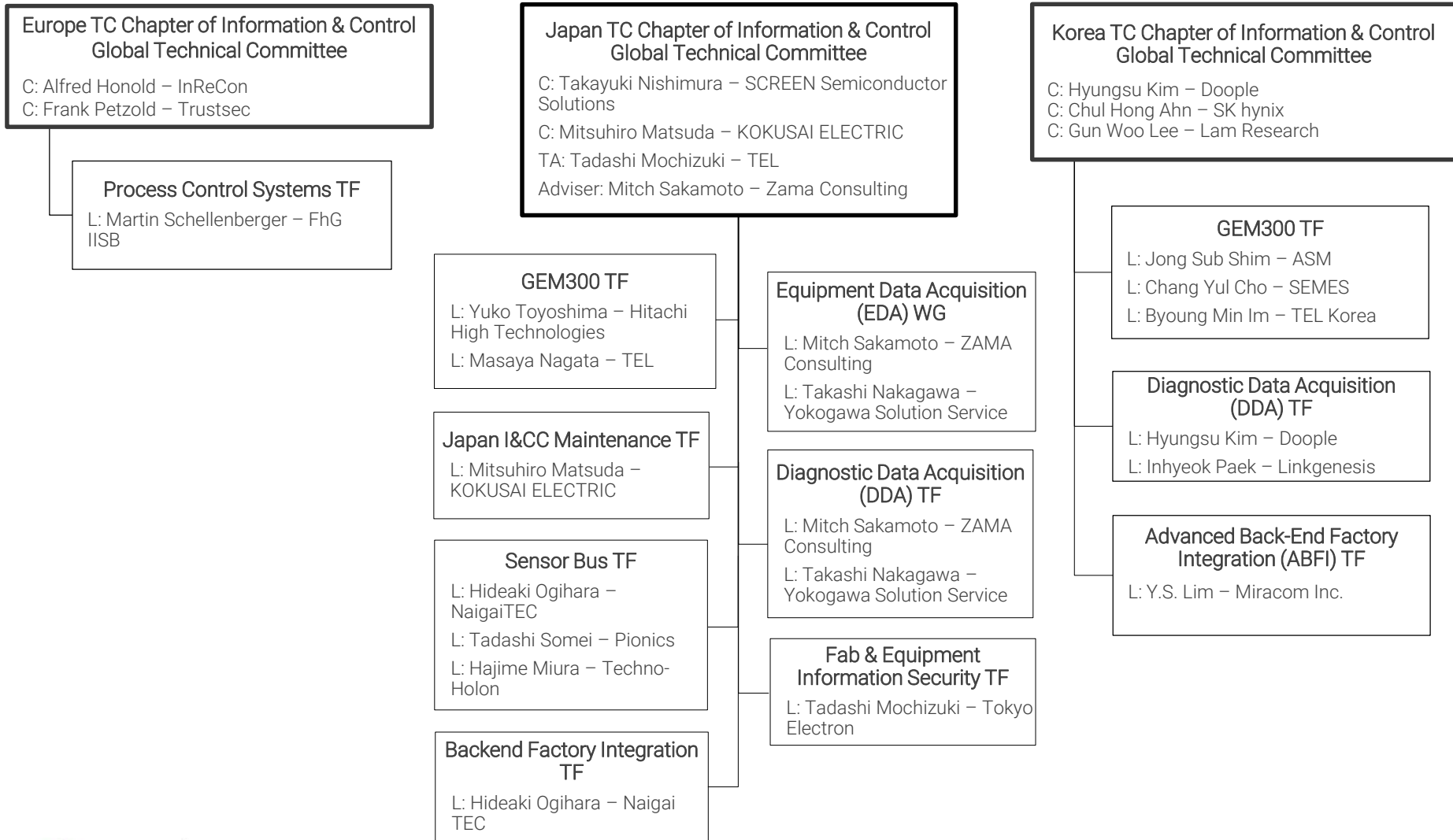
HB-LED Impurities & Defects in Sapphire Wafers TF (Inactive)

L: Luke Gliński – GT Advanced Technologies

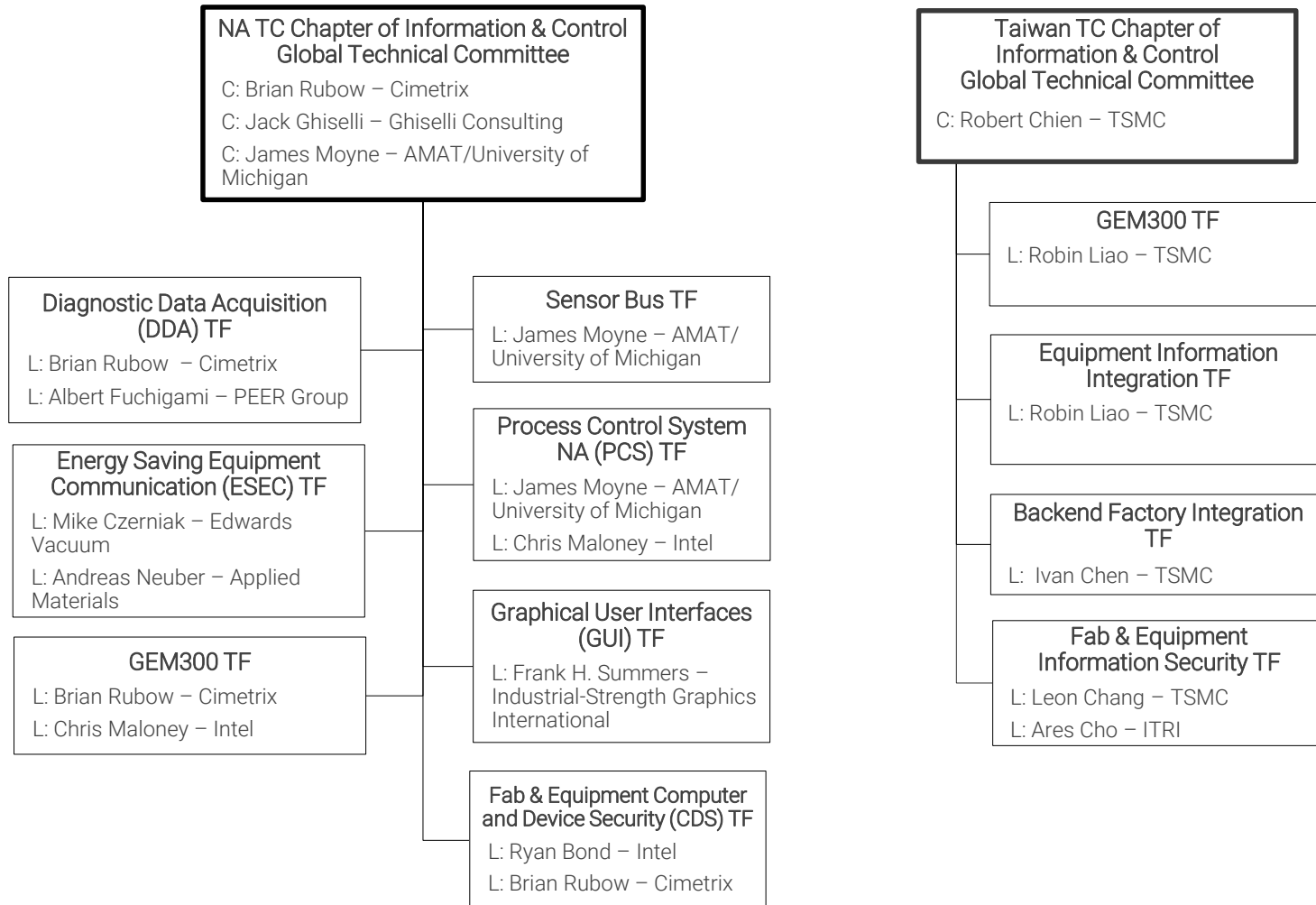
HB-LED Source Materials TF (Korea)

L: Paul Ahn – Veeco
L: H.B. Joo – Aixtron
L: Sungjin Jun – LG Innotek
L: Deok-gil – Samsung Electronics

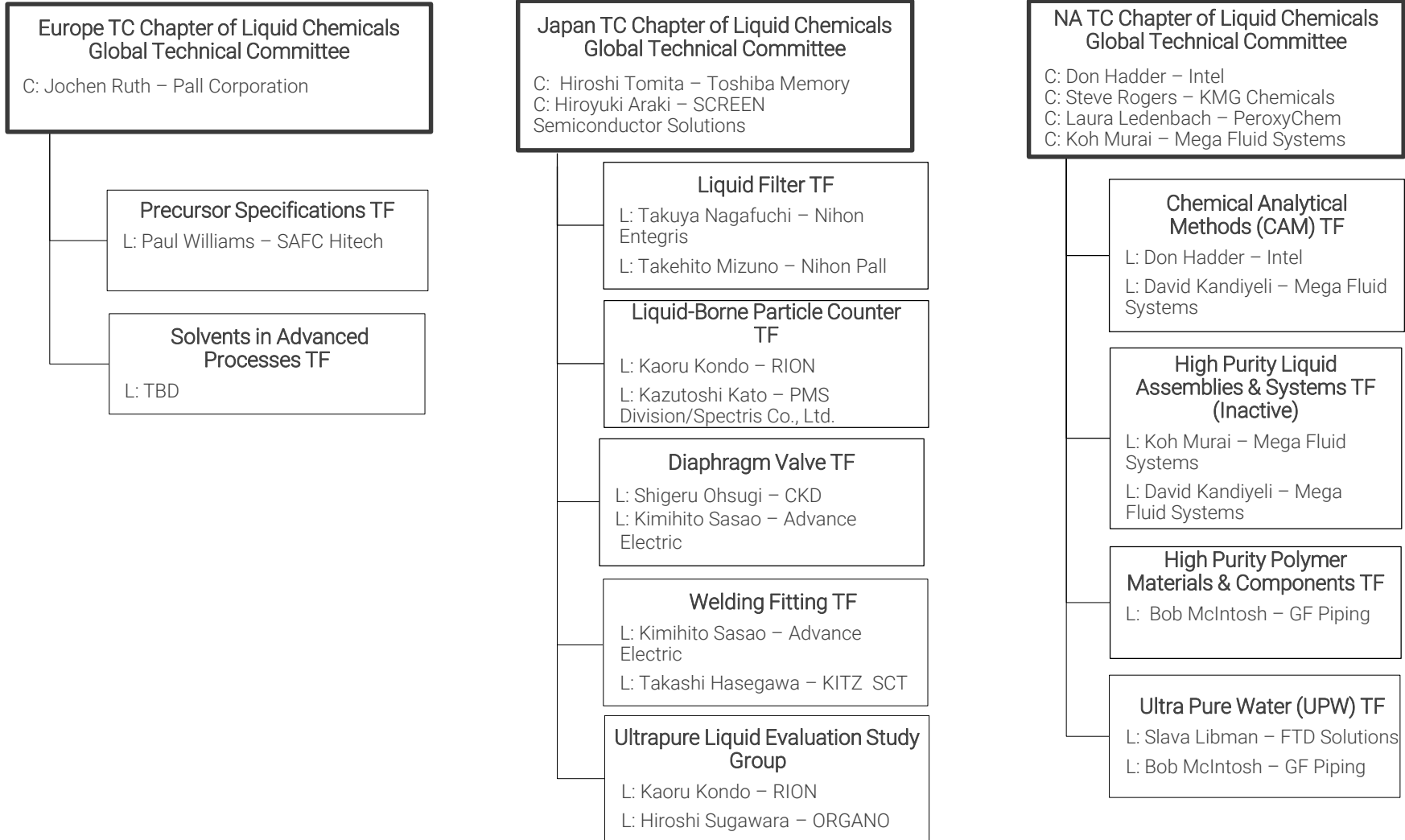
Information & Control (I&C) Global Technical Committee



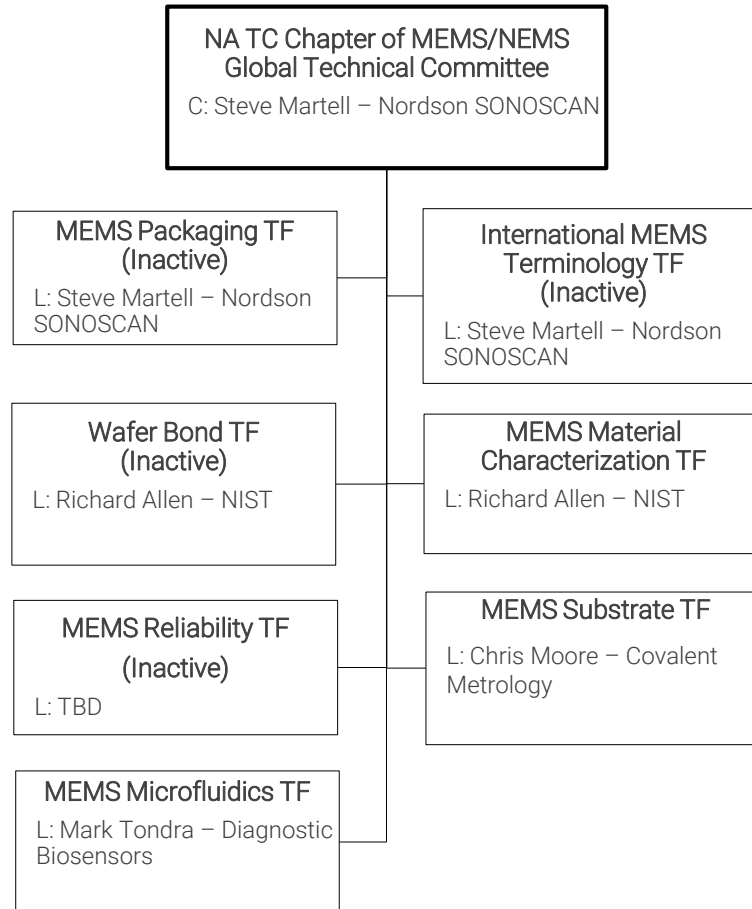
Information & Control (I&C) Global Technical Committee



Liquid Chemicals Global Technical Committee

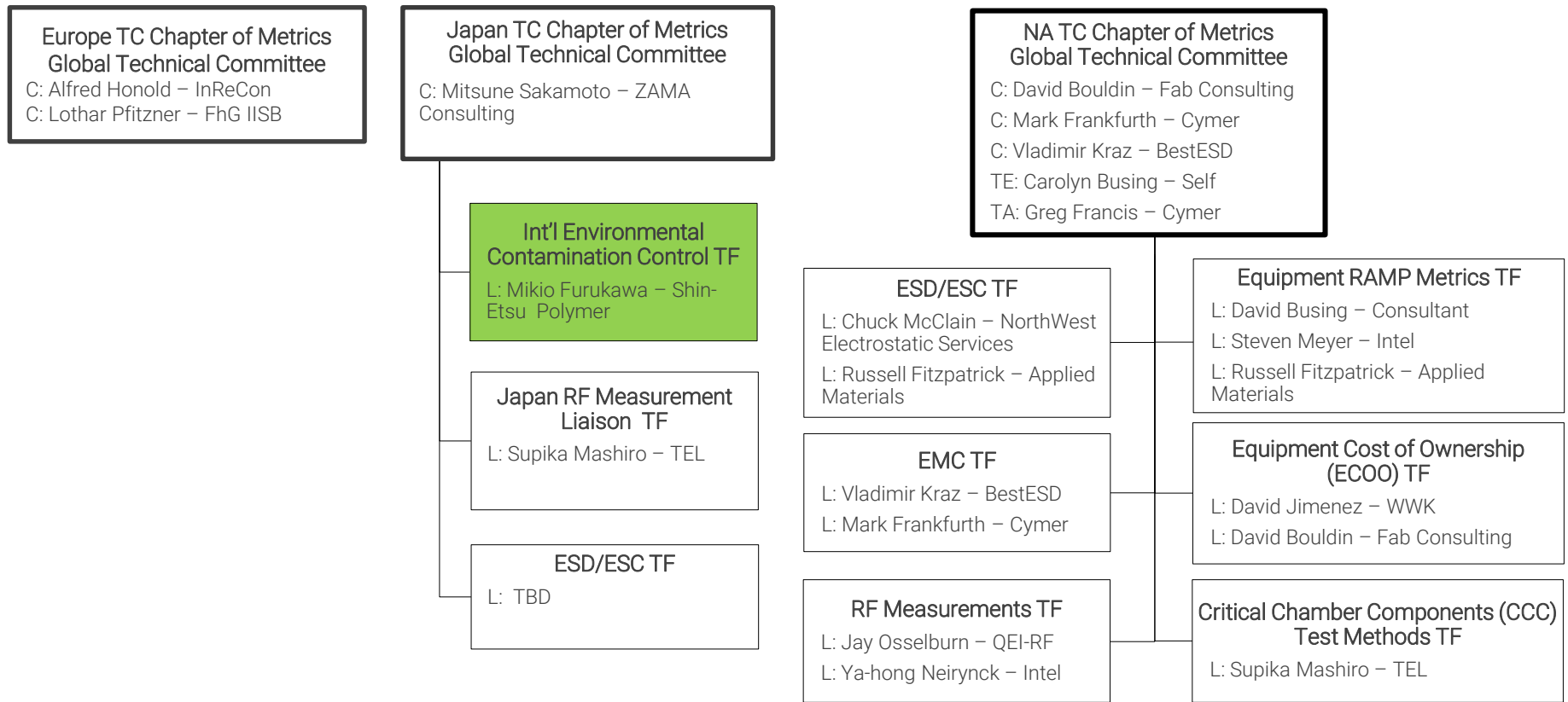



MEMS/NEMS Global Technical Committee



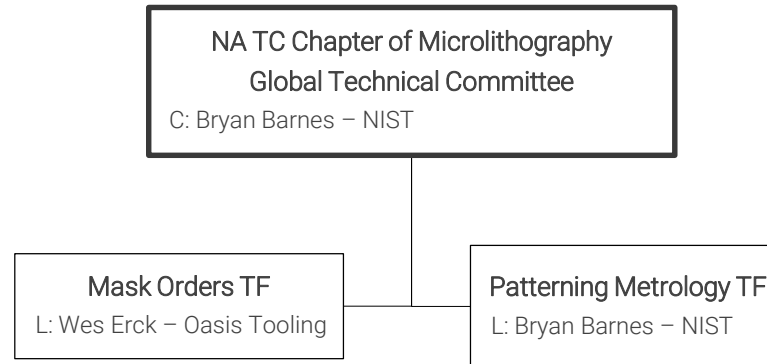
Metrics

Global Technical Committee

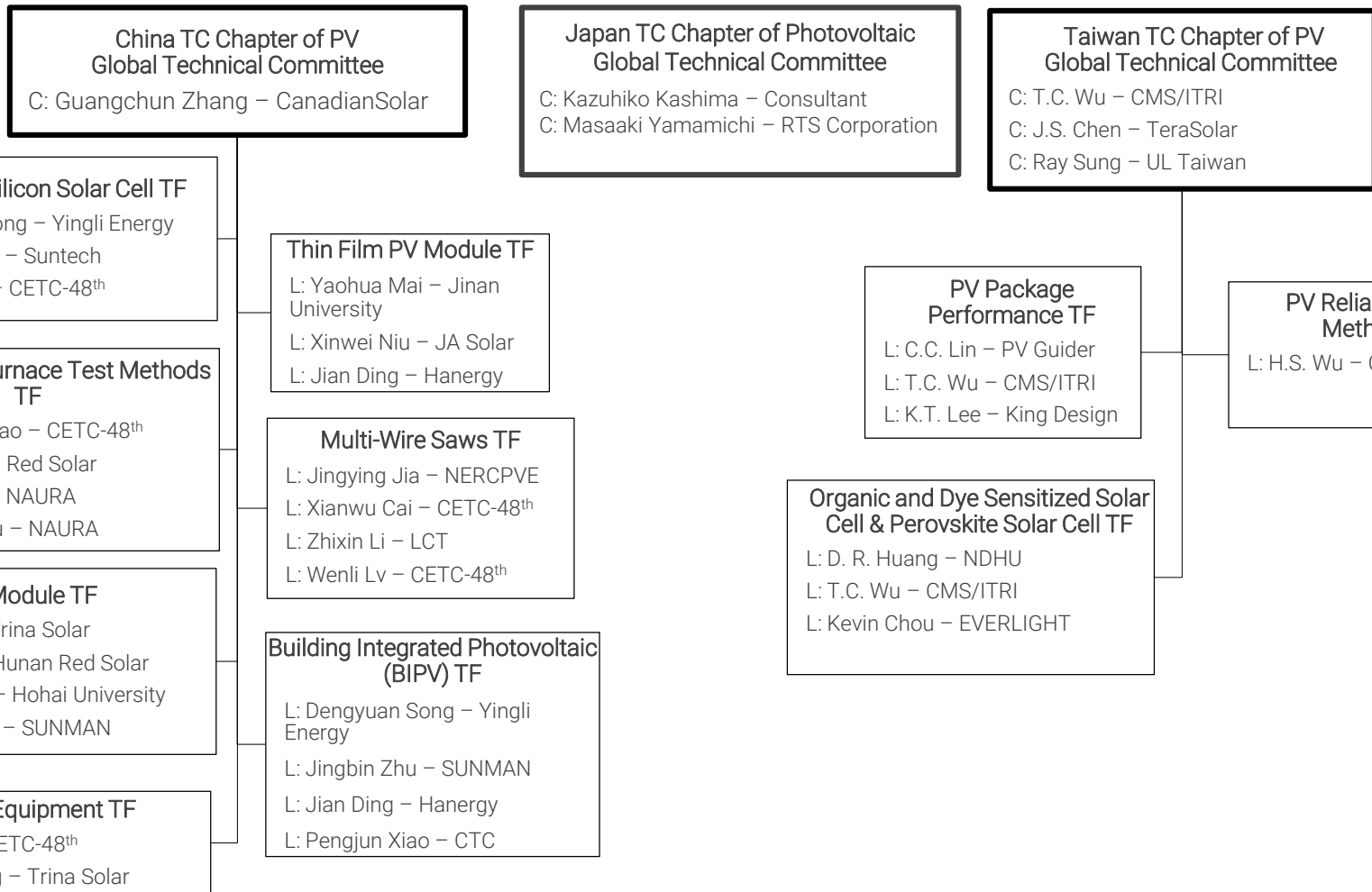


 = Global Task Force

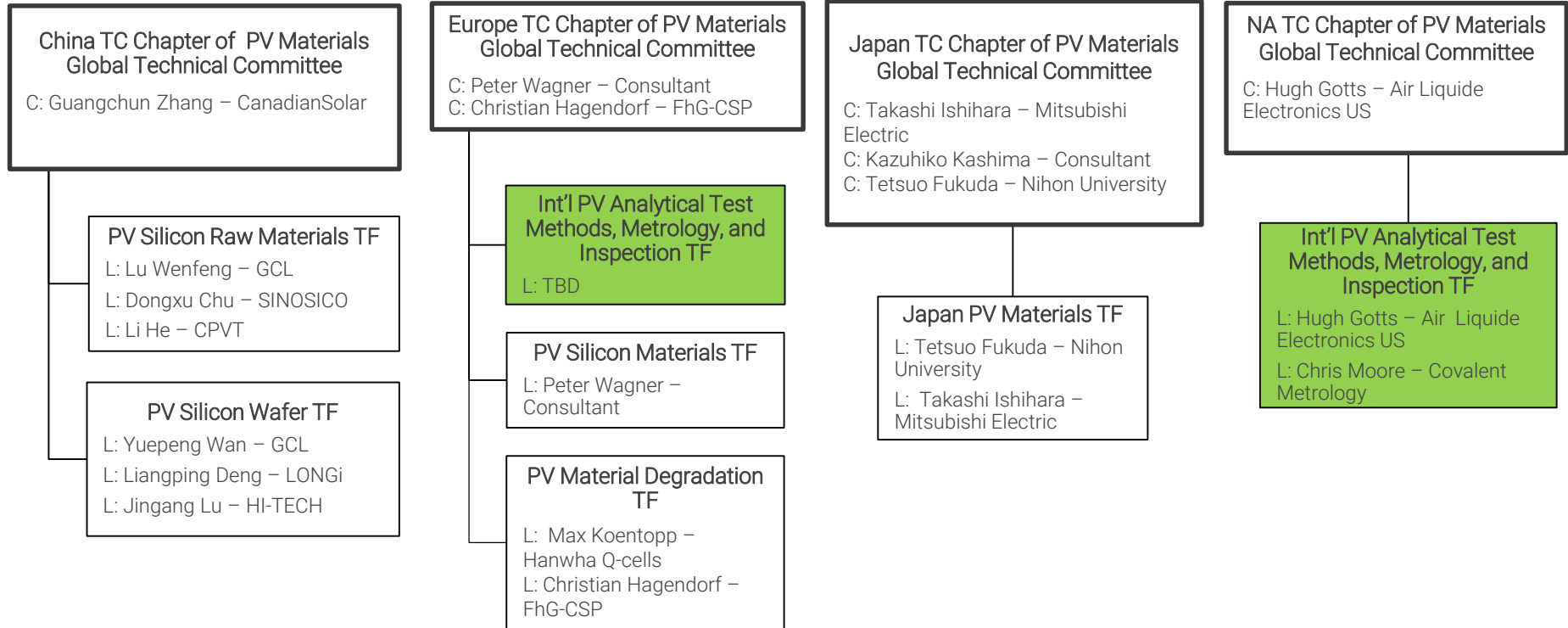
Micropatterning Global Technical Committee




Photovoltaic (PV) Global Technical Committee

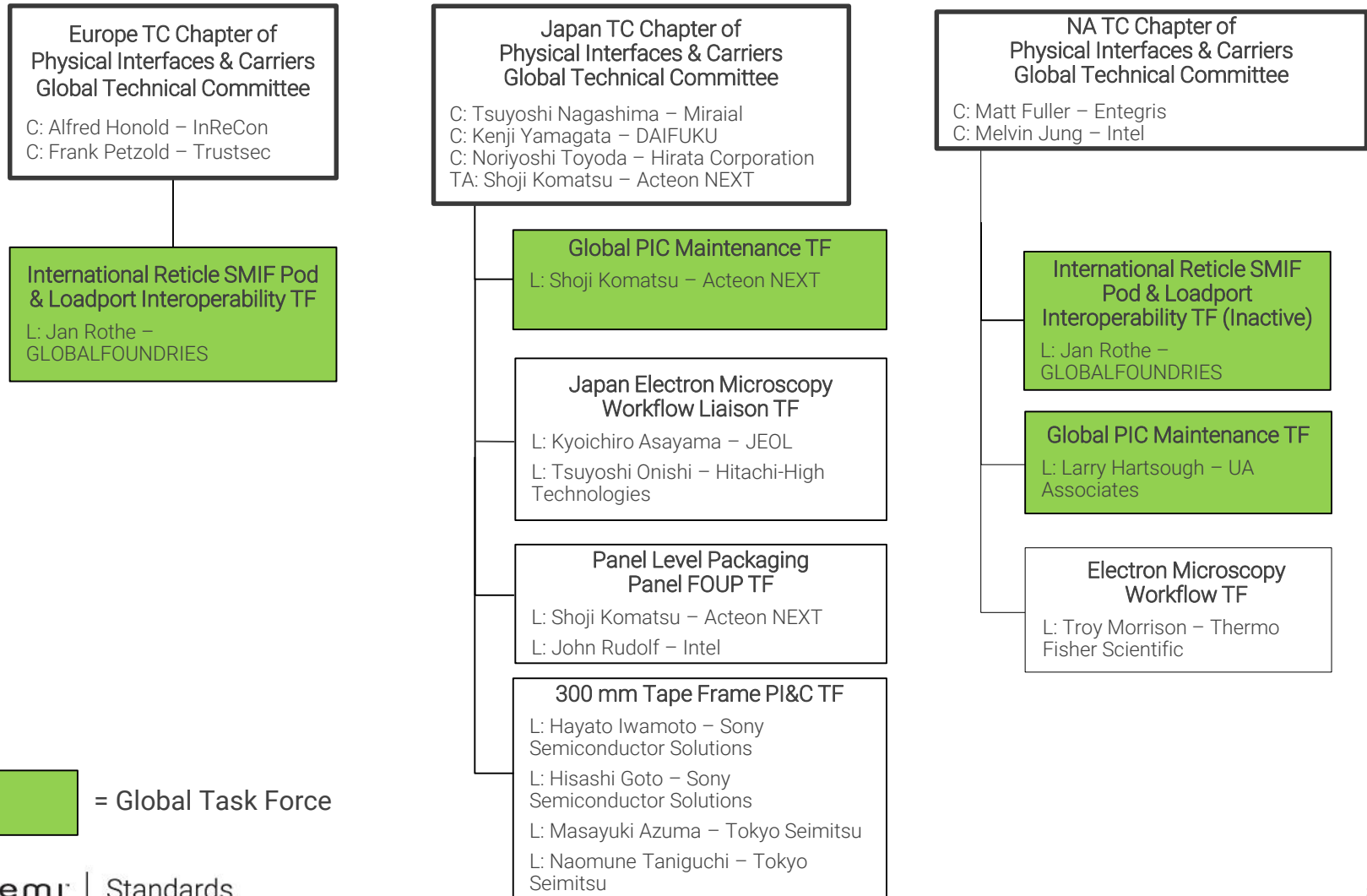


PV Materials Global Technical Committee

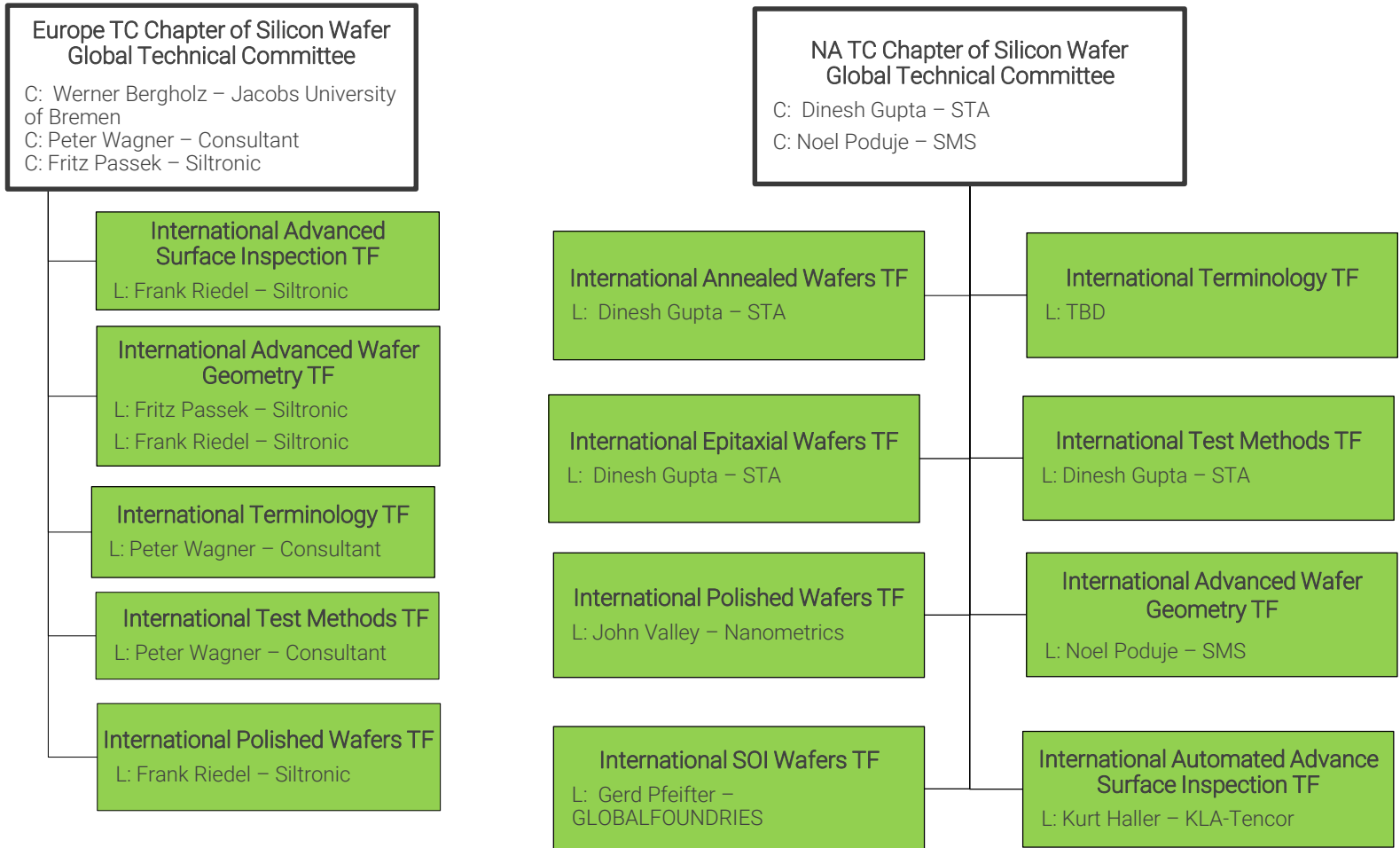



 = Global Task Force

Physical Interfaces & Carriers (PIC) Global Technical Committee

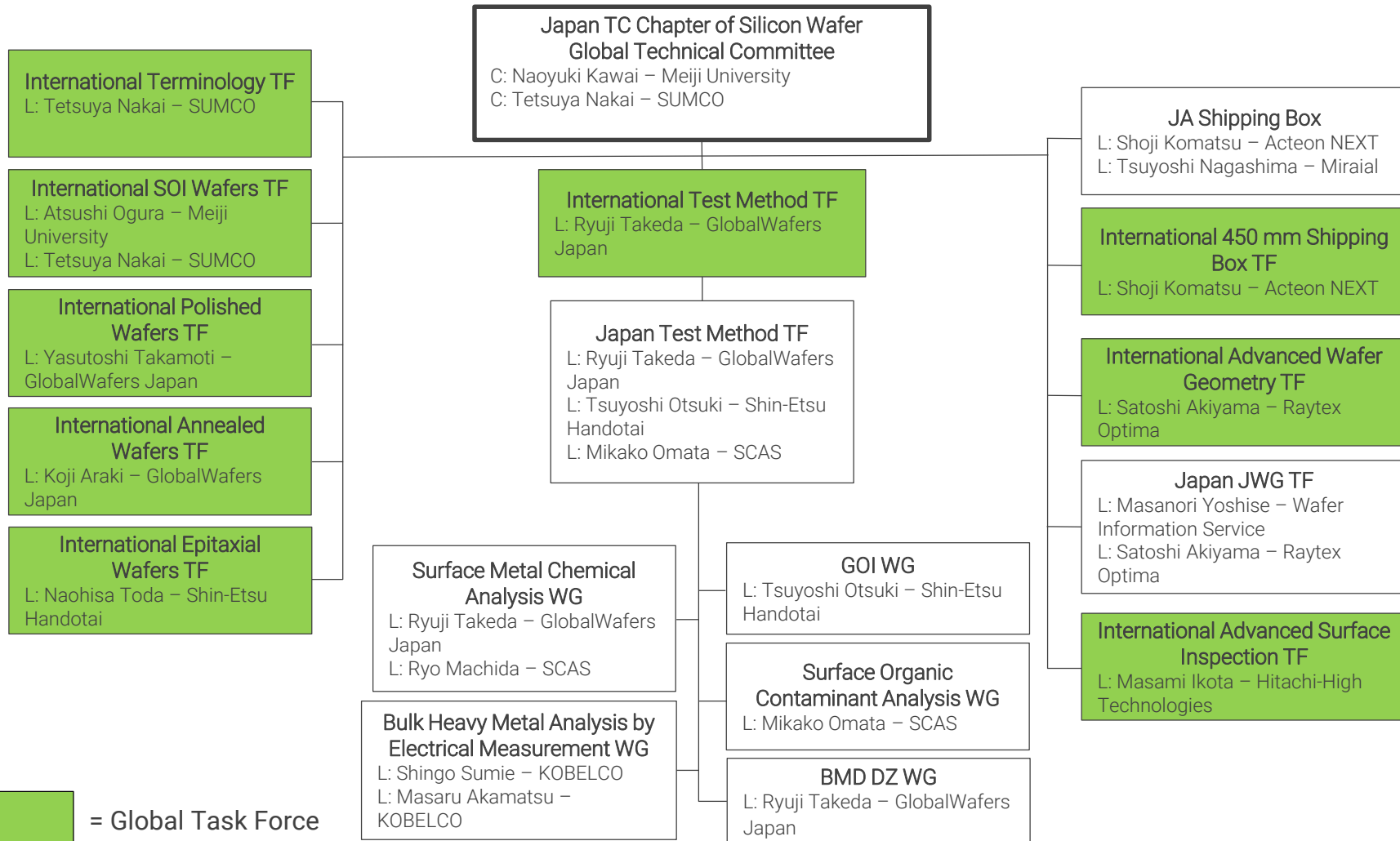


Silicon Wafer Global Technical Committee



 = Global Task Force

Silicon Wafer Global Technical Committee



Traceability Global Technical Committee

